

Listing of the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-14. (Cancelled)

15. (Previously presented) A wafer polishing system comprising:
a first chemical-mechanical polishing station having a polishing portion;
a source of an oxidizer-free medium;
a source of an oxidizing medium; and
a delivery system adapted for delivering said oxidizer-free medium to a wafer in said polishing station prior to delivering said oxidizing medium to said wafer in said polishing station;
wherein said source of an oxidizer-free medium and said source of an oxidizing medium are maintained separately.
16. (Original) The wafer polishing system of claim 15, further comprising:
a second polishing station; and
a transfer mechanism adapted to move said wafer from said first polishing station to said second polishing station.
17. (Previously presented) A wafer polishing system comprising:
a first polishing station adapted to polish a surface of a wafer in the presence of an oxidizer-free medium;
a source of an oxidizer-free medium;
a second polishing station adapted to polish said surface of said wafer in the presence of an oxidizing medium;
a source of an oxidizing medium;
a transfer mechanism adapted to move a wafer to and from said first polishing station and said second polishing station; and
a delivery system,
wherein said delivery system is adapted to deliver said oxidizer-free medium to said first polishing station in order to polish said wafer;

wherein said transfer mechanism is adapted to move said wafer to said second polishing station; and

wherein said delivery system is adapted to deliver said oxidizing medium to said second station in order to polish said wafer.

18. (Previously presented) The wafer polishing system of claim 17, wherein said delivery system is adapted to deliver said oxidizing solution to said first polishing station.

19. (Previously presented) The wafer polishing system of claim 17, further comprising:

a second source of an oxidizing medium; and

wherein said delivery system is adapted to deliver said second source of oxidizing medium to said first polishing station.

20. (Original) The wafer polishing station of claim 17, wherein said oxidizer-free medium comprises an oxidizer-free slurry, and said oxidizing medium comprises an oxidizing slurry.

21. (Previously presented) A wafer polishing system comprising:
a plurality of polishing stations;
a delivery system adapted for supplying an oxidizer-free medium to at least one of said polishing stations to polish a surface of a wafer and for supplying an oxidizing medium to at least one of said polishing stations to polish said wafer surface; and
a transfer mechanism adapted to move said wafer among said plurality of polishing stations;

wherein said delivery system and said transfer mechanism act cooperatively to supply oxidizer-free medium onto a specific wafer surface prior to supplying oxidizing medium onto said specific wafer surface.

22. (Previously presented) The wafer polishing system of claim 21, wherein said oxidizer-free medium and said oxidizing medium are delivered to the same polishing station.

23. (Previously presented) The wafer polishing system of claim 21, wherein said oxidizer-free medium and said oxidizing medium are delivered to different polishing stations.

24. (Previously presented) The wafer polishing system of claim 15, wherein said delivery system discontinues delivering said oxidizer-free medium to said wafer in said polishing

station and subsequently begins delivering said oxidizing medium to said wafer in said polishing station.

25. (Previously presented) The wafer polishing system of claim 17, wherein said transfer mechanism moves said wafer from said first polishing station to said second polishing station.